

Prototype Assembly Services

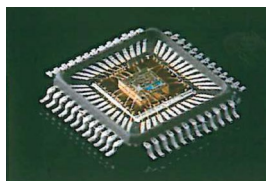
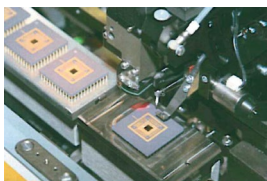
QP Technologies delivers completely assembled prototype devices in as little as one day – enabling faster design verification and quicker time to market for your new products.

Whether you need die assembled in our proprietary Open Cavity Plastic or ceramic packages, multichip modules, chip-on-board or surface-mount boards, we use state-of-the-art assembly equipment and processes to meet your needs.



Capabilities:

- Wafer dicing and backgrinding
- Numerous die attach options
- Wire bonding with 0.8 to 3.0 mil gold wire
- Extensive encapsulation options
- Remolding and branding
- Same-day turnaround available
- Ideal for rapid prototype assembly, design verification and customer samples



Our capabilities include:

- **Wafer Dicing and Backgrinding** - Dicing of wafers up to 300mm in diameter and backgrinding down to 7 mils.
- **Die Attach** - Using standard conductive or nonconductive epoxy or your qualified die attach material.
- **Wire Bond** - Automatic bonding equipment can accommodate wire diameters from 0.8 to 3.0 mils, and bond pad pitch down to 40 microns.
- **Encapsulation Options** - QP Technologies offers a vast array of choices to meet your testing needs, ranging from open cavity to full encapsulation.
- **Remolding** - Prototypes meet JEDEC standards for test socket and auto-handling compatibility.
- **Branding** - Pad-print a logo, part number and/or date code for clear identification.

When you need to meet a project or customer deadline, you can count on QP Technologies' reliable on-time delivery options for assembly – from standard three-day turnaround to one-day or even same-day expedited service.

Make QP Technologies' high-quality prototype assembly service part of your product development and verification process.

Verisys Registrars®

ISO 9001:2015 Certified
ISO 13485:2016 Certified



QP Technologies is an ITAR
Registered Company.